

### *Amendments to the Claims*

The listing of claims will replace all prior versions, and listings of claims in the application.

1. (currently amended) A cleaning device for process gases that is configured to generate clean process gas from contaminated process gas in a reflow soldering system, comprising:

a cleaning chamber comprising [[,]] first and second series-connected modules, configured to have different operative principles of deposition, which are connected one after the other in series,

wherein the first series-connected module comprises,

a cleaning liquid configured to clean the contaminated process gas, said cleaning chamber allowing the contaminated process gas to flow therein via ~~a supply line~~ a second series-connected module and allowing the cleaned process gas to flow therefrom via a discharge line;

a first deposition wall having a first surface, the surface being configured to receive a film of the cleaning liquid and being configured to be an outer wall of the cleaning device; and

a second deposition wall positioned centrally within the cleaning chamber and having a second surface facing the first surface, the second surface being configured to receive another film of the cleaning liquid; and

wherein the second series-connected module comprises,

a bath comprising the cleaning liquid, and

a supply line coupled below a liquid level of the bath and configured to allow the contaminated process gas to flow therein and rise upwards in bubbles in the bath.

2. (canceled)

3. (currently amended) The device according to claim 2 1, wherein a flow path for the cleaning liquid extends through the series-connected modules in such a manner that the direction of flow of the cleaning liquid is opposite to the direction of flow of the process gas.

4. (currently amended) The cleaning device according to claim 10, further comprising a plurality of cleaning liquids having different cleaning properties, such that respective ones of which are provided in respective ones of the plurality of ~~modules~~ cleaning chambers arranged in the successive order.

5 - 6. (canceled)

7. (previously presented) The cleaning device according to claim 1, wherein there are a plurality of the first and second deposition walls that are arranged perpendicular or with a slope with respect to each other in the cleaning chamber and a supply for the cleaning liquid is arranged in an area on top of edges of the plurality of first and second deposition walls.

8. (previously presented) The cleaning device according to claim 1, wherein at least one respective injection opening for the cleaning liquid is directed into the cleaning chamber.

9. (previously presented) The cleaning device according to claim 1, wherein the cleaning chamber comprises a respective outlet that is connected to a clarifying device for the cleaning liquid.

10. (currently amended) The cleaning device according to claim 1, wherein the ~~cleaning chamber~~ cleaning device comprises a plurality of ~~modules~~ cleaning chambers arranged in parallel configured to allow for a predetermined throughput and, in successive order, to allow for a predetermined degree of purity for the process gas.

11. (currently amended) A system, comprising:  
a cleaning chamber comprising first and second series-connected modules, configured to have different operative principles of deposition, which are connected one after the other in series,

wherein the first series-connected module comprises,  
a plurality of separate deposition walls each having a surface, the surface being configured to receive a film of a cleaning liquid that is configured to clean a contaminated process gas, the contaminated process gas flowing into the plurality of separate deposition walls via ~~a supply line~~ a second series-connected module and from the plurality of separate deposition walls via a discharge line,

wherein a supply for the cleaning liquid is arranged in an area on top of edges of the plurality of separate deposition walls,

wherein at least one of the plurality of separate deposition walls is an inner surface of an outer wall of the system, and

wherein a respective one of the plurality of separate deposition walls is centrally located within the system and has first and second surfaces, the first and second surfaces each being configured to receive another film of the cleaning liquid; and

wherein the second series-connected module comprises,

a bath comprising the cleaning liquid, and

a supply line coupled below a liquid level of the bath and configured to allow the contaminated process gas to flow therein and rise upwards in bubbles in the bath.

12. (canceled)

13. (currently amended) The device according to claim ~~12~~ 11, wherein a flow path for the cleaning liquid extends through the series-connected modules in such a manner that the direction of flow of the cleaning liquid is opposite to the direction of flow of the process gas.

14. (currently amended) The cleaning device according to claim 19, further comprising a plurality of cleaning liquids having different cleaning properties, such that respective ones of which are provided in respective ones of each of the ~~modules~~ cleaning chambers arranged in the successive order.

15. (canceled)

16. (previously presented) The cleaning device according to claim 11, wherein the plurality of separate deposition walls are arranged perpendicular or with a slope with respect to each other.

17. (previously presented) The cleaning device according to claim 11, wherein at least one respective injection opening for the cleaning liquid is directed into the plurality of separate deposition walls.

18. (previously presented) The cleaning device according to claim 11, wherein the plurality of separate deposition walls comprises a respective outlet that is connected to a clarifying device for the cleaning liquid.

19. (currently amended) The ~~cleaning device~~ system according to claim 11, wherein the ~~plurality of separate deposition walls~~ system comprises a plurality of ~~modules~~ cleaning chambers arranged in parallel configured to allow for a predetermined throughput and, in successive order, to allow for a predetermined degree of purity for the process gas.

20. (currently amended) A cleaning device for process gases that is configured to generate clean process gas from contaminated process gas in a reflow soldering system, comprising:

a cleaning chamber configured to allow the contaminated process gas to flow therein via a supply line and the cleaned process gas to flow therefrom via a discharge line, the cleaning chamber comprising first and second series-connected modules, configured to have different operative principles of deposition, which are connected one after the other in series,  
wherein the first series-connected module comprises,

at least one first deposition wall having a first surface, the surface being configured to receive a film of cleaning liquid and being configured to be an outer wall of the cleaning device;

at least one second deposition wall positioned centrally within the cleaning chamber and having a second surface facing the first surface, the second surface being configured to receive another film of the cleaning liquid;

a supply for the cleaning liquid arranged internally in the cleaning chamber in an upper area of the at least one first deposition wall and the at least one second deposition

wall, configured to provide the films of cleaning liquid such that the films of cleaning liquid trap contaminants and flow downward along the at least one first deposition wall and the at least one second deposition wall, the supply for the cleaning liquid constantly replacing the films of cleaning liquid; and

an outlet configured to collect the cleaning liquid and trapped contaminants at a lower area of the cleaning chamber; and

wherein the second series-connected module comprises a bath comprising the cleaning liquid, and

wherein the supply line is coupled below a liquid level of the bath and is configured to allow the contaminated process gas to flow therein and rise upwards in bubbles in the bath.